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PATENT  
NON-FINAL

PATENT APPLN. NO. 10/609,022  
RESPONSE UNDER 37 C.F.R. §1.111

IN THE CLAIMS:

1. (currently amended) A method of adhering a coating of a polymer, ~~metal~~, metalloid oxide or fluorinated derivatives thereof to a surface of a dielectric layer or passivation layer of a device produced in a CMOS process comprising applying to said surface, as an adhesion promoter, a hybrid organic-inorganic material which is partially or fully fluorinated.

2. (original) The method of claim 1, wherein said inorganic portion of said hybrid material comprises silicon.